

FEATURES

Dual transceivers for RS-422

ESD protection on bus input/output pins

±15 kV human body model (HBM)

±8 kV IEC 61000-4-2, contact discharge

±8 kV IEC 61000-4-2, air discharge

Complies with TIA/EIA-422-B and ITU-T recommendation V.11

Open-circuit fail-safe

Suitable for 5 V power supply applications

Low supply current operation: 9 mA maximum

Low driver output skew

Receiver input impedance: 30 kΩ

Receiver common-mode range: -7 V to +7 V

Power-up/power-down without glitches

16-pin TSSOP package

Operating temperature range: -40°C to +85°C

APPLICATIONS

RS-422 interfaces

High data rate motor control

Single-ended-to-differential signal conversion

Point-to-point and multidrop transmission systems

FUNCTIONAL BLOCK DIAGRAM

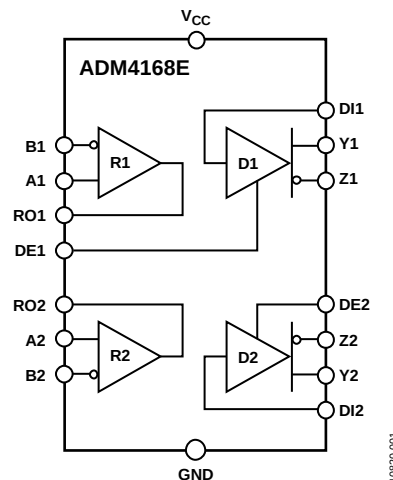


Figure 1.

GENERAL DESCRIPTION

The [ADM4168E](#) has dual RS-422 transceivers suitable for high speed communication on point-to-point and multidrop transmission lines. The [ADM4168E](#) is designed for balanced transmission lines and complies with TIA/EIA-422-B.

The differential driver outputs and receiver inputs feature electrostatic discharge circuitry that provides protection up to ±15 kV HBM and ±8 kV IEC 61000-4-2 (contact and air discharge).

The [ADM4168E](#) operates from a single 5 V power supply. Excessive power dissipation caused by bus contention or output shorting is prevented by short-circuit protection circuitry. Short-circuit protection circuits limit the maximum output current to 150 mA during fault conditions.

The receivers of the [ADM4168E](#) contain a fail-safe feature that results in a logic high output state if the inputs are unconnected (floating).

The [ADM4168E](#) is fully specified over the commercial and industrial temperature ranges and is available in a 16-pin TSSOP package.

Rev. 0

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REVISION HISTORY

9/12—Revision 0: Initial Version

SPECIFICATIONS

4.5 V $\leq$ V_{CC} $\leq$ 5.5 V; all minimum/maximum specifications apply over the entire recommended operation range, unless otherwise noted.
All typical specifications are at T_A = 25°C, V_{CC} = 5.0 V, unless otherwise noted.

Table 1.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
SUPPLY CURRENT						No load, drivers enabled
Total Package	I _{CC}		4	6	mA	V _I = V _{CC} or GND
			5	9	mA	V _I = 2.4 V or 0.5 V ¹
DRIVER						
Differential Outputs (Y1, Z1, Y2, Z2 Pins)						
Input Clamp Voltage	V _{IK}			−1.5	V	I _I = −18 mA
Output Voltage High	V _{OH}	2.4	3.5		V	V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = −20 mA
Output Voltage Low	V _{OL}		0.2	0.4	V	V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 20 mA
Differential Output Voltage						
No Load	V _{OD1}	2.0		6.0	V	I _O = 0 mA
Outputs Loaded ²	V _{OD2}	2.0	3.7		V	R _L = 100 Ω (see Figure 11)
Δ V _{OD} for Complementary Output States	Δ V _{OD}			±0.4	V	R _L = 100 Ω (see Figure 11)
Common-Mode Output Voltage	V _{OC}			±3.0	V	R _L = 100 Ω (see Figure 11)
Δ V _{OC} for Complementary Output States	Δ V _{OC}			±0.4	V	R _L = 100 Ω (see Figure 11)
Output Leakage Current	I _O			100	μA	DE = 0 V, V _{CC} = 0 V or 5 V, V _O = 6 V
		−100			μA	DE = 0 V, V _{CC} = 0 V or 5 V, V _O = −0.25 V
Output Current (Short Circuit) ³	I _{OS}	−30		−150	mA	V _O = V _{CC} or GND
Input Capacitance	C _I		6		pF	
Logic Inputs (DI, DE Pins)						
Input Voltage High	V _{IH}	2.0			V	
Input Voltage Low	V _{IL}			0.8	V	
Input Current High	I _{IH}			1	μA	V _I = V _{CC} or V _{IH}
Input Current Low	I _{IL}			−1	μA	V _I = GND or V _{IL}
RECEIVER						
Differential Inputs (A1, B1, A2, B2 Pins)						
Differential Input Threshold Voltage ²	V _{TH}	−200		+200	mV	
Input Voltage Hysteresis	V _{HYS}		60		mV	
Input Current	I _I			1.5	mA	V _I = 7 V, other input at 0 V
				−2.5	mA	V _I = −7 V, other input at 0 V
Line Input Resistance	R _{IN}	12	30		kΩ	V _{IC} = −7 V to +7 V, other input at 0 V
Logic Outputs (RO1, RO2 Pins)						
Output Voltage High	V _{OH}	3.8	4.2		V	V _{ID} = 200 mV, I _{OH} = −6 mA
Output Voltage Low	V _{OL}		0.1	0.3	V	V _{ID} = −200 mV, I _{OL} = 6 mA

¹ Measured per input with other inputs at V_{CC} or GND.

² For exact conditions, see TIA/EIA-422-B.

³ No more than one output shorted at any time, with the duration of the short not to exceed 1 second.

TIMING SPECIFICATIONS

4.5 V $\leq V_{CC} \leq 5.5$ V; all minimum/maximum specifications apply over the entire recommended operation range, unless otherwise noted.
All typical specifications are at $T_A = 25^\circ\text{C}$, $V_{CC} = 5.0$ V, unless otherwise noted.

Table 2.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
DRIVER						$R_1, R_2 = 50\ \Omega$; $R_3 = 500\ \Omega$; $C_1, C_2, C_3 = 40\ \text{pF}$
Propagation Delay	t_{DPLH}, t_{DPHL}		8	16	ns	S1 open (see Figure 12 and Figure 13)
Driver Output Skew	t_{SK}		1.5	4	ns	S1 open (see Figure 12 and Figure 13)
Rise Time/Fall Time	t_{DR}, t_{DF}		5	10	ns	S1 open (see Figure 12 and Figure 13)
Enable Time	t_{ZH}, t_{ZL}		10	19	ns	S1 closed (see Figure 13 and Figure 14)
Disable Time	t_{HZ}, t_{LZ}		7	16	ns	S1 closed (see Figure 13 and Figure 14)
RECEIVER ¹						
Propagation Delay	t_{RPLH}, t_{RPHL}	9	15	27	ns	$C_L = 50\ \text{pF}$ (see Figure 15 and Figure 16)
Transition Time	t_{TLH}, t_{THL}		4	9	ns	$V_{IC} = 0\ \text{V}$, $C_L = 50\ \text{pF}$ (see Figure 15 and Figure 16)

¹ Measured per input with other inputs at V_{CC} or GND.

ABSOLUTE MAXIMUM RATINGS

Table 3.

Parameter	Rating
V_{CC}	−0.3 V to +7 V
Digital Input Voltage (DE1, DE2)	−0.3 V to +7 V
Driver Input Voltage (DI1, DI2)	−0.3 V to +7 V
Receiver Output Voltage (RO1, RO2)	−0.3 V to $V_{CC} + 0.3$ V
Driver Output Voltage (Y1, Z1, Y2, Z2)	−0.3 V to +7 V
Receiver Input Voltage (A1, B1, A2, B2)	−14 V to +14 V
Operating Temperature Range	−40°C to +85°C
Storage Temperature Range	−65°C to +150°C
ESD Protection on Ax, Bx, Yx, and Zx	
Human Body Model (HBM)	±15 kV
IEC 61000-4-2, Contact Discharge	±8 kV
IEC 61000-4-2, Air Discharge	±8 kV

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL RESISTANCE

θ_{JA} is specified for the worst-case conditions, that is, a device soldered in a circuit board for surface-mount packages.

Table 4. Thermal Resistance

Package Type	θ_{JA}	Unit
16-Lead TSSOP	113	°C/W

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

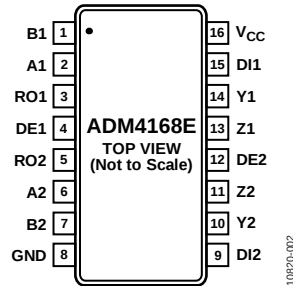


Figure 2. Pin Configuration

Table 5. Pin Function Descriptions

Pin No.	Mnemonic	Description
1	B1	Inverting Receiver Input B, Transceiver 1.
2	A1	Noninverting Receiver Input A, Transceiver 1.
3	RO1	Receiver Output, Transceiver 1.
4	DE1	Driver Output Enable, Transceiver 1. A logic high enables the differential driver outputs, Y1 and Z1; a logic low places the differential driver outputs in a high impedance state.
5	RO2	Receiver Output, Transceiver 2.
6	A2	Noninverting Receiver Input A, Transceiver 2.
7	B2	Inverting Receiver Input B, Transceiver 2.
8	GND	Ground.
9	DI2	Driver Input, Transceiver 2. When the driver is enabled, a logic low on DI2 forces Y2 low and Z2 high, whereas a logic high on DI2 forces Y2 high and Z2 low.
10	Y2	Noninverting Driver Output Y, Transceiver 2.
11	Z2	Inverting Driver Output Z, Transceiver 2.
12	DE2	Driver Output Enable, Transceiver 2. A logic high enables the differential driver outputs, Y2 and Z2; a logic low places the differential driver outputs in a high impedance state.
13	Z1	Inverting Driver Output Z, Transceiver 1.
14	Y1	Noninverting Driver Output Y, Transceiver 1.
15	DI1	Driver Input, Transceiver 1. When the driver is enabled, a logic low on DI1 forces Y1 low and Z1 high, whereas a logic high on DI1 forces Y1 high and Z1 low.
16	V _{CC}	Power Supply (5 V ± 10%).

TYPICAL PERFORMANCE CHARACTERISTICS

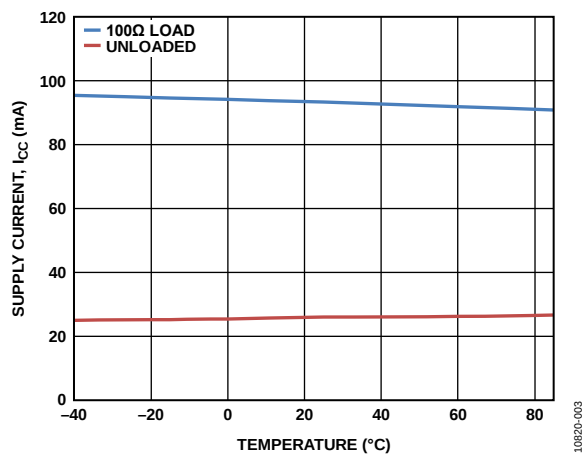


Figure 3. Supply Current vs. Temperature, Data Rate = 10 Mbps

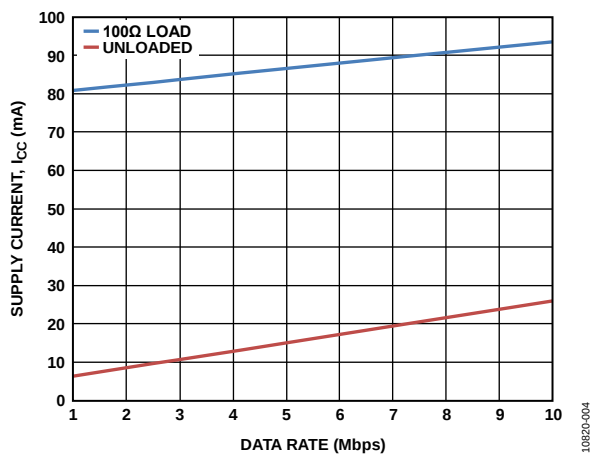


Figure 6. Supply Current vs. Data Rate

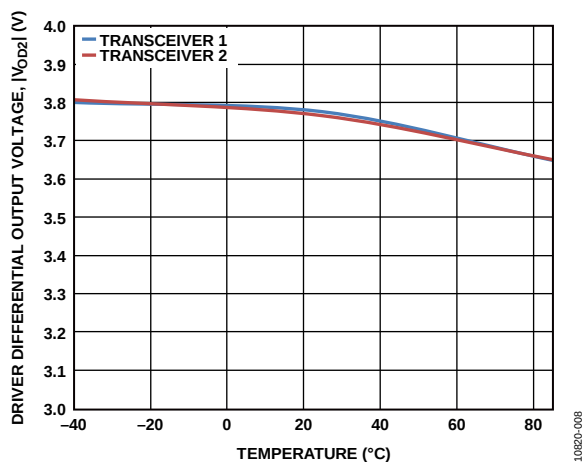


Figure 4. Driver Differential Output Voltage vs. Temperature

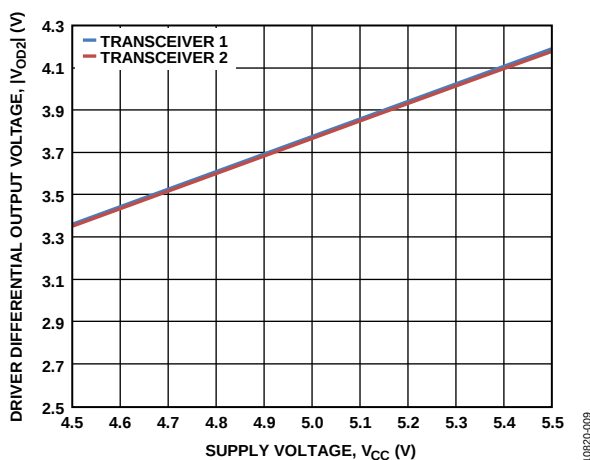


Figure 7. Driver Differential Output Voltage vs. Supply Voltage

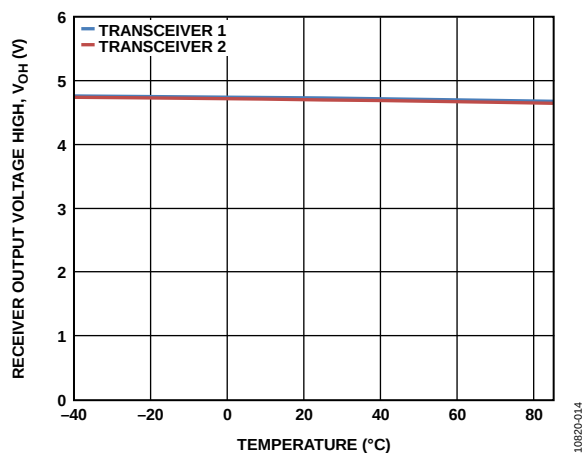


Figure 5. Receiver Output Voltage High vs. Temperature

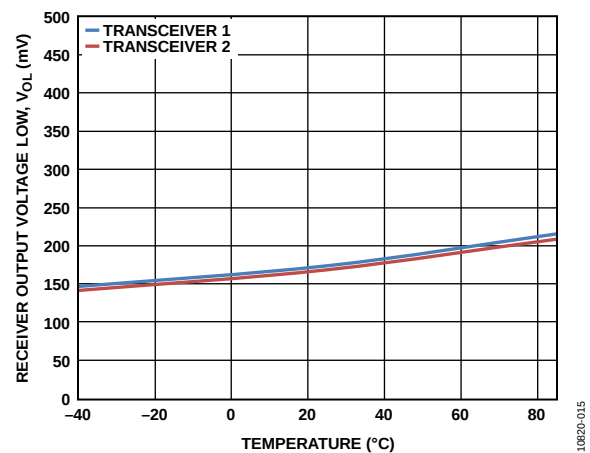


Figure 8. Receiver Output Voltage Low vs. Temperature

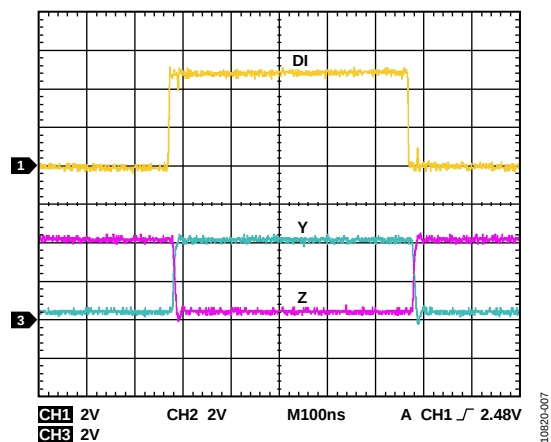


Figure 9. Driver Output

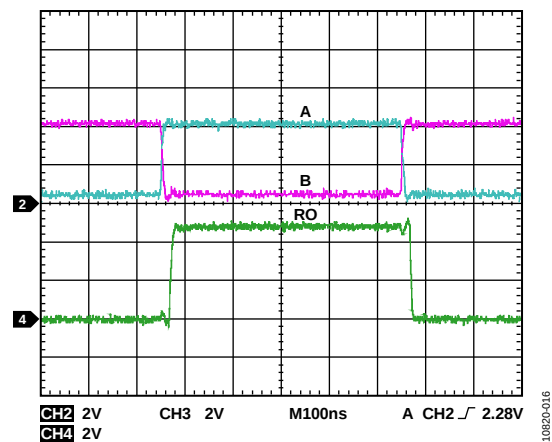


Figure 10. Receiver Output

TEST CIRCUITS AND SWITCHING CHARACTERISTICS

DRIVER MEASUREMENTS

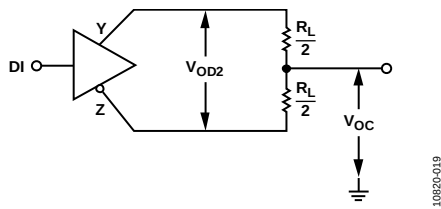
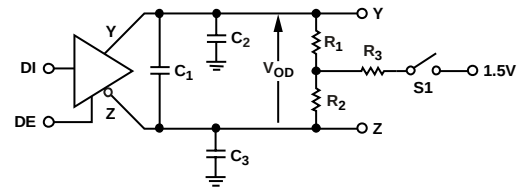
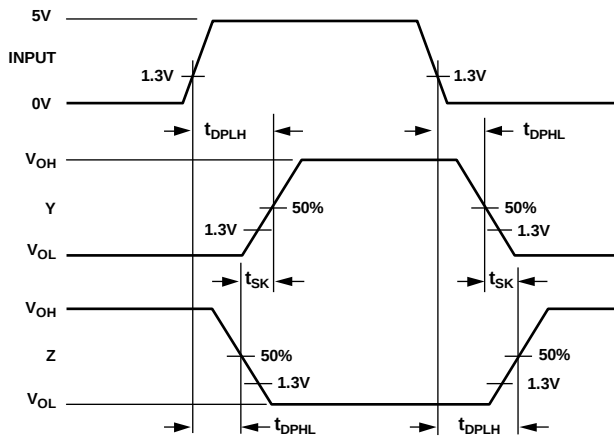


Figure 11. Driver Voltage Measurements



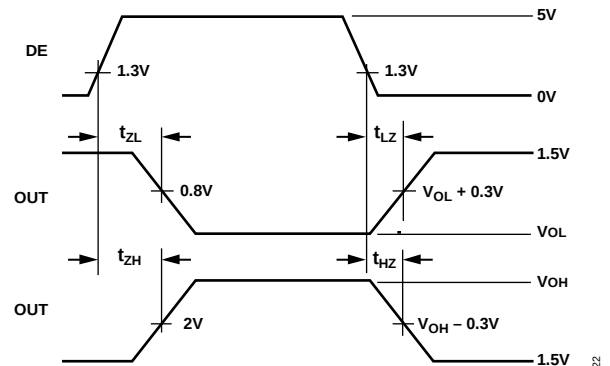
NOTES
1. C_1 , C_2 , C_3 INCLUDE PROBE/INSTRUMENT CAPACITANCE.

Figure 13. Driver Timing Circuit



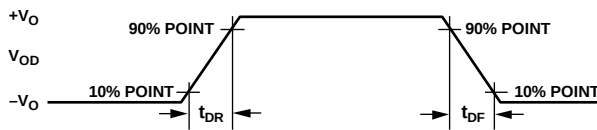
NOTES
1. INPUT PULSE GENERATOR: PPR 1MHz; 50% DUTY CYCLE; t_R , $t_F \leq 6\text{ns}$.

Figure 12. Driver Propagation Delay and Rise/Fall Timing



NOTES
1. INPUT PULSE GENERATOR: PPR 1MHz; 50% DUTY CYCLE; t_R , $t_F \leq 6\text{ns}$.

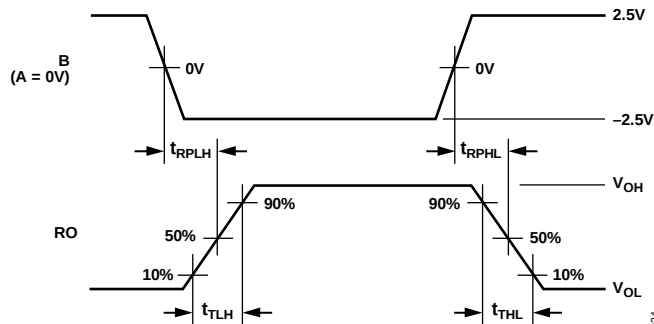
Figure 14. Driver Enable/Disable Timing



NOTES
1. INPUT PULSE GENERATOR: PPR 1MHz; 50% DUTY CYCLE; t_R , $t_F \leq 6\text{ns}$.

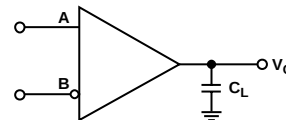
Figure 12. Driver Propagation Delay and Rise/Fall Timing

RECEIVER MEASUREMENTS



NOTES
1. INPUT PULSE GENERATOR: PPR 1MHz; 50% DUTY CYCLE; t_R , $t_F \leq 6\text{ns}$.

Figure 15. Receiver Propagation Delay and Transition Timing



NOTES
1. C_L INCLUDES PROBE/INSTRUMENT CAPACITANCE.

Figure 16. Receiver Timing Circuit

THEORY OF OPERATION

The [ADM4168E](#) is a dual RS-422 transceiver that operates from a single 5 V $\pm$ 10% power supply. The [ADM4168E](#) is intended for balanced data transmission and complies with TIA/EIA-422-B and ITU-T recommendation V.11. Each device contains two differential line drivers and two differential line receivers and is suitable for full-duplex data transmission.

The receivers contain a fail-safe feature that results in a logic high output state if the inputs are unconnected (floating).

The [ADM4168E](#) features a low propagation delay, ensuring maximum baud rate operation. The balanced driver ensures distortion-free transmission.

Another important specification is a measure of the skew between the complementary outputs. Low skew enhances the noise immunity of the system and decreases the amount of electromagnetic interference (EMI).

TRUTH TABLES

Table 6. Abbreviations in Truth Tables

Letter	Description
H	High level
I	Indeterminate
L	Low level
X	Irrelevant
Z	High impedance (off)

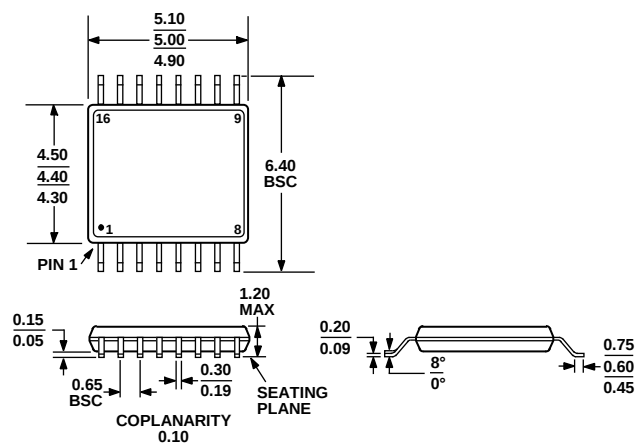
Table 7. Transmitting (Each Driver)

Inputs		Outputs	
DE	DI	Z	Y
H	H	L	H
H	L	H	L
L	X	Z	Z

Table 8. Receiving (Each Receiver)

Inputs	Output
A – B	RO
$\geq +0.2\text{ V}$	H
$\leq -0.2\text{ V}$	L
$-0.2\text{ V} < A - B < +0.2\text{ V}$	I
Inputs open	H

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-153-AB

Figure 17. 16-Lead Thin Shrink Small Outline Package [TSSOP]
(RU-16)

Dimensions shown in millimeters

ORDERING GUIDE

Model ¹	Temperature Range	Package Description	Package Option
ADM4168EBRUZ	−40°C to +85°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
ADM4168EBRUZ-RL7	−40°C to +85°C	16-Lead Thin Shrink Small Outline Package [TSSOP]	RU-16
EVAL-ADM4168EEBZ		Evaluation Board	

¹ Z = RoHS Compliant Part.

NOTES

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

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Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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